

## N-Channel 600 V (D-S) MOSFET

PRODUCT SUMMARY			
V <sub>DS</sub> (V)	R <sub>DS(on)</sub> (Ω) (Typ.)	I <sub>D</sub> (A) <sup>a</sup>	Q <sub>g</sub> (Typ.)
600	25 at V <sub>GS</sub> = 10 V	0.4	7.2 nC

### FEATURES

- DT-Trench Power MOSFET
- 100 % R<sub>g</sub> and UIS Tested

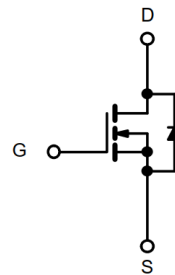
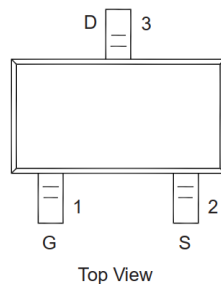


**RoHS**  
COMPLIANT

### APPLICATIONS

- Power Management for Portable and Consumer
  - Load Switches
  - DC/DC Converters

SOT-23-3L Pin Configuration



N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS (T <sub>C</sub> = 25 °C, unless otherwise noted)			
PARAMETER	SYMBOL	LIMIT	UNIT
Drain-Source Voltage	V <sub>DS</sub>	600	V
Gate-Source Voltage	V <sub>GS</sub>	± 30	
Continuous Drain Current (T <sub>J</sub> = 150 °C)	I <sub>D</sub>	T <sub>C</sub> = 25 °C	0.4
		T <sub>C</sub> = 70 °C	0.25
Pulsed Drain Current	I <sub>DM</sub>	1.5	A
Maximum Power Dissipation <sup>a</sup>	P <sub>D</sub>	T <sub>C</sub> = 25 °C	0.4
		T <sub>C</sub> = 70 °C	0.256
Operating Junction and Storage Temperature Range	T <sub>J</sub> , T <sub>stg</sub>	-55 to +150	°C

THERMAL RESISTANCE RATINGS			
PARAMETER	SYMBOL	LIMIT	UNIT
Junction-to-Ambient (PCB Mount) <sup>b</sup>	R <sub>thJC</sub>	312	°C/W

Notes:

a. T<sub>C</sub> = 25 °C.

b. Surface mounted on 1" x 1" FR4 board.

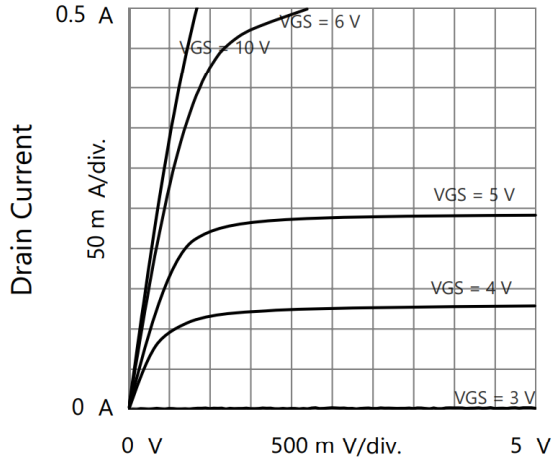
SPECIFICATIONS ( $T_J = 25\text{ }^\circ\text{C}$ , unless otherwise noted)						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT
<b>Static</b>						
Drain-Source Breakdown Voltage	$V_{DS}$	$V_{GS} = 0\text{ V}, I_D = 250\text{ }\mu\text{A}$	600	-	-	V
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\text{ }\mu\text{A}$	2	-	4	
Gate-Body Leakage	$I_{GSS}$	$V_{DS} = 0\text{ V}, V_{GS} = \pm 20\text{ V}$	-	-	$\pm 100$	nA
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS} = 600\text{ V}, V_{GS} = 0\text{ V}$	-	-	1	$\mu\text{A}$
On-State Drain Current <sup>a</sup>	$I_{D(on)}$	$V_{DS} \geq 5\text{ V}, V_{GS} = 10\text{ V}$	0.4	-	-	A
Drain-Source On-State Resistance <sup>a</sup>	$R_{DS(on)}$	$V_{GS} = 10\text{ V}, I_D = 0.2\text{ A}$	-	25	30	$\Omega$
Forward Transconductance <sup>a</sup>	$g_{fs}$	$V_{DS} = 15\text{ V}, I_D = 0.2\text{ A}$	-	0.9	-	S
<b>Dynamic <sup>b</sup></b>						
Input Capacitance	$C_{iss}$	$V_{GS} = 0\text{ V}, V_{DS} = 25\text{ V}, f = 1\text{ MHz}$	-	160	-	pF
Output Capacitance	$C_{oss}$		-	22	-	
Reverse Transfer Capacitance	$C_{rss}$		-	4	-	
Total Gate Charge <sup>c</sup>	$Q_g$	$V_{DS} = 15\text{ V}, V_{GS} = 4.5\text{ V}, I_D = 0.4\text{ A}$	-	7.2	-	nC
Gate-Source Charge <sup>c</sup>	$Q_{gs}$		-	1.2	-	
Gate-Drain Charge <sup>c</sup>	$Q_{gd}$		-	3.1	-	
Gate Resistance	$R_g$	$f = 1\text{ MHz}$	-	6.7	-	$\Omega$
Turn-On Delay Time	$t_{d(on)}$	$V_{DD} = 300\text{ V}, I_D = 0.4\text{ A},$ $V_{GS} = 10\text{ V}, R_g = 0\text{ }\Omega$	-	8	-	ns
Rise Time	$t_r$		-	5	-	
Turn-Off Delay Time	$t_{d(off)}$		-	16	-	
Fall Time	$t_f$		-	22	-	
<b>Drain-Source Body Diode Ratings and Characteristics <sup>b</sup> (<math>T_C = 25\text{ }^\circ\text{C}</math>)</b>						
Continuous Source Current	$I_S$	$T_C = 25\text{ }^\circ\text{C}$	-	-	0.4	A
Pulsed Source Current	$I_{SM}$		-	-	1.5	A
Forward Voltage <sup>a</sup>	$V_{SD}$	$I_S = 0.4\text{ A}, V_{GS} = 0\text{ V}$	-	-	1.6	V
Body Diode Reverse Recovery Time	$t_{rr}$	$I_F = 1\text{ A}, di/dt = 100\text{ A}/\mu\text{s}, T_J = 25\text{ }^\circ\text{C}$	-	178	-	ns
Body Diode Reverse Recovery Charge	$Q_{rr}$		-	288	-	nC
Reverse Recovery Fall Time	$t_a$		-	37	-	ns
Reverse Recovery Rise Time	$t_b$		-	141	-	

**Notes**

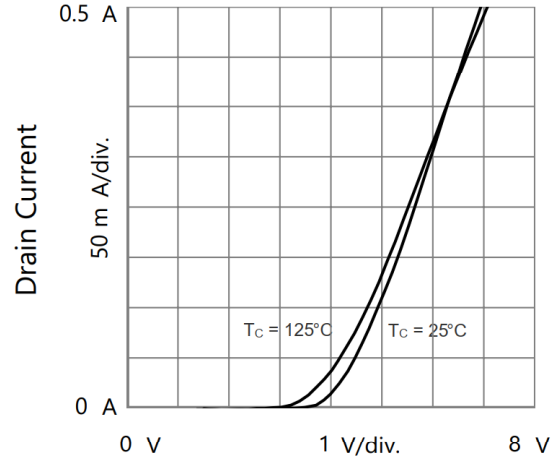
- Pulse test; pulse width  $\leq 300\text{ }\mu\text{s}$ , duty cycle  $\leq 2\%$ .
- Guaranteed by design, not subject to production testing.
- Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

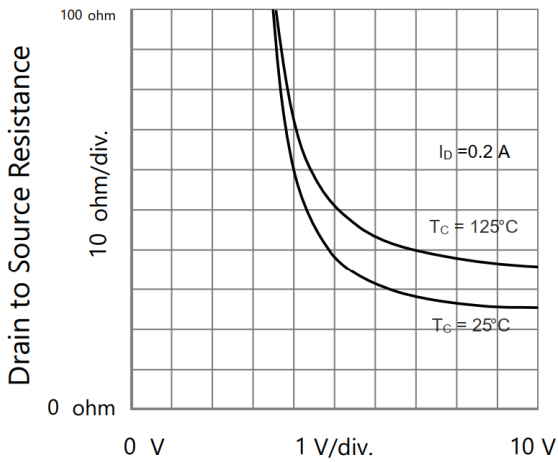
**TYPICAL CHARACTERISTICS** (25 °C, unless otherwise noted)



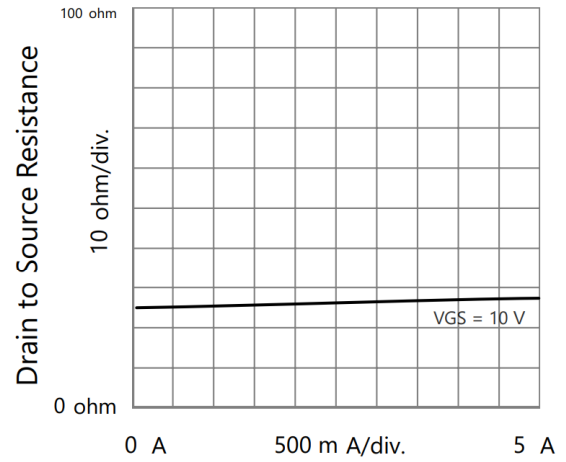
Drain to Source Voltage  
Output Characteristics



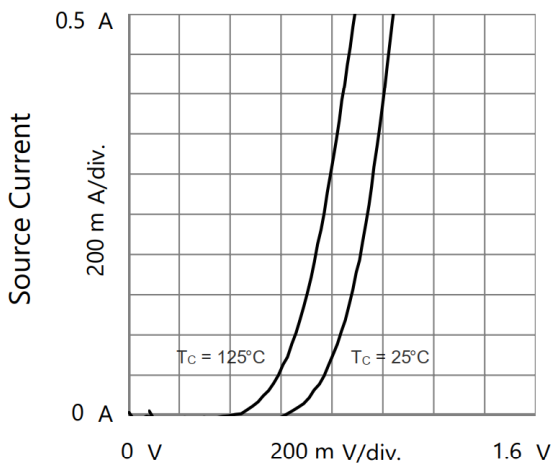
Gate to Source Voltage  
Transfer Characteristics



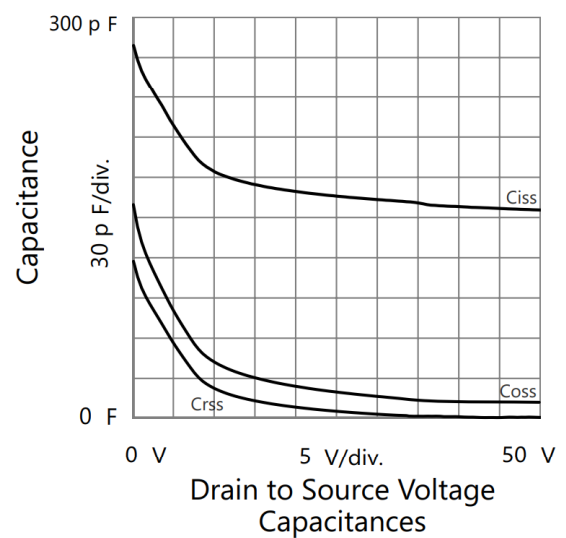
Gate to Source Voltage  
Drain to Source Resistance vs. Gate to Source Voltage



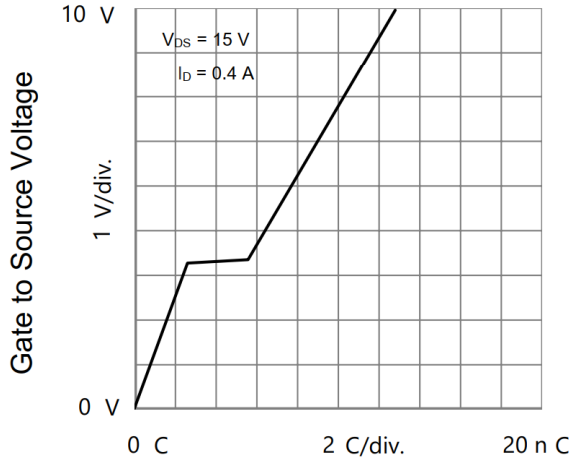
Drain Current  
Drain to Source Resistance vs. Drain Current



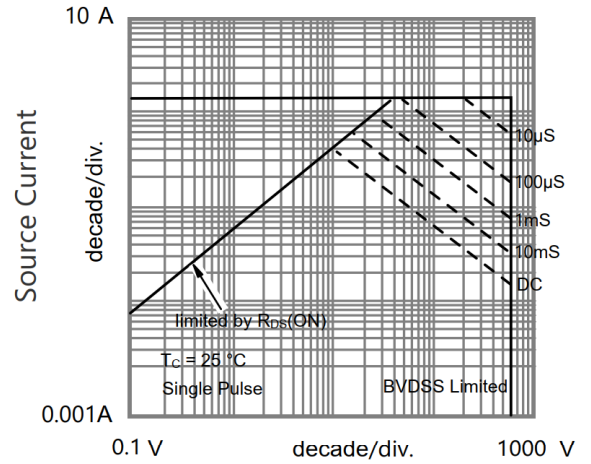
Source to Drain Voltage  
Body Diode Forward Characteristics



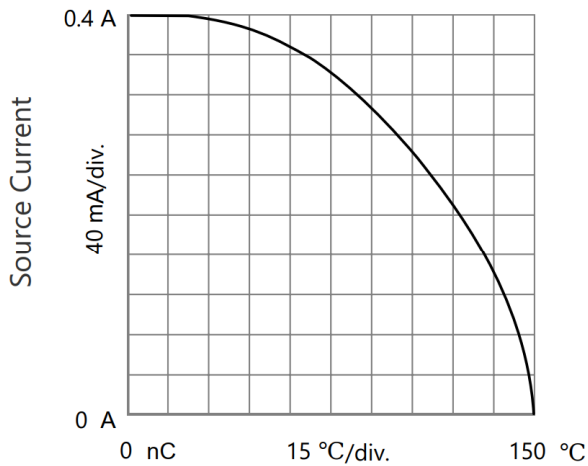
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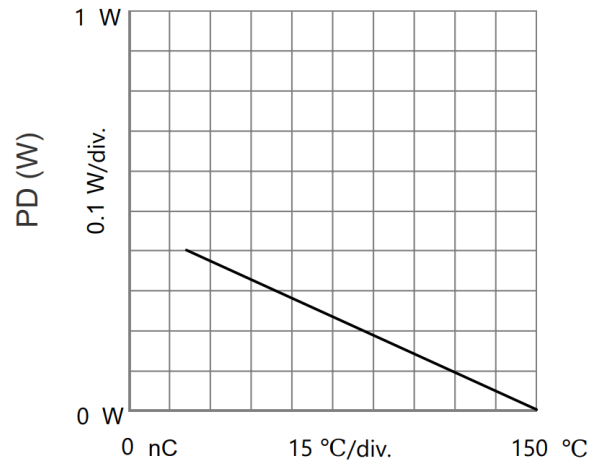
**Gate to Source Voltage vs. Gate Charge**



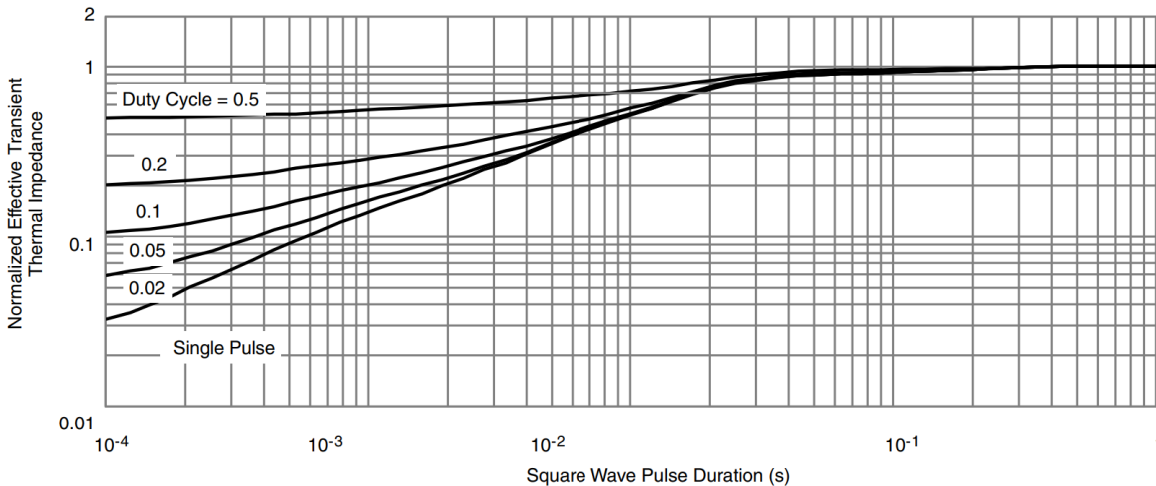
**Source to Drain Voltage**  
Safe Operating Area, Junction-to-Ambient



**T<sub>C</sub> - Case Temperature**  
Current Derating

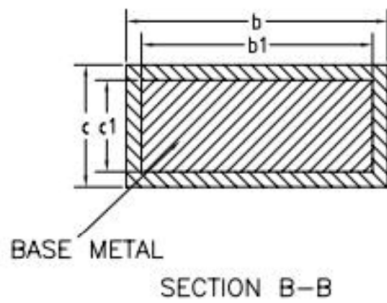
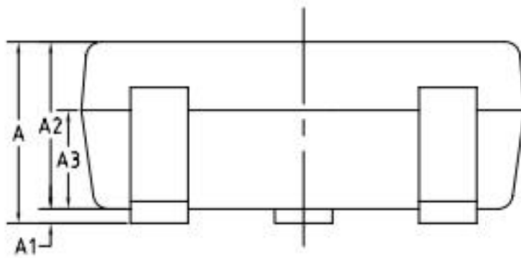
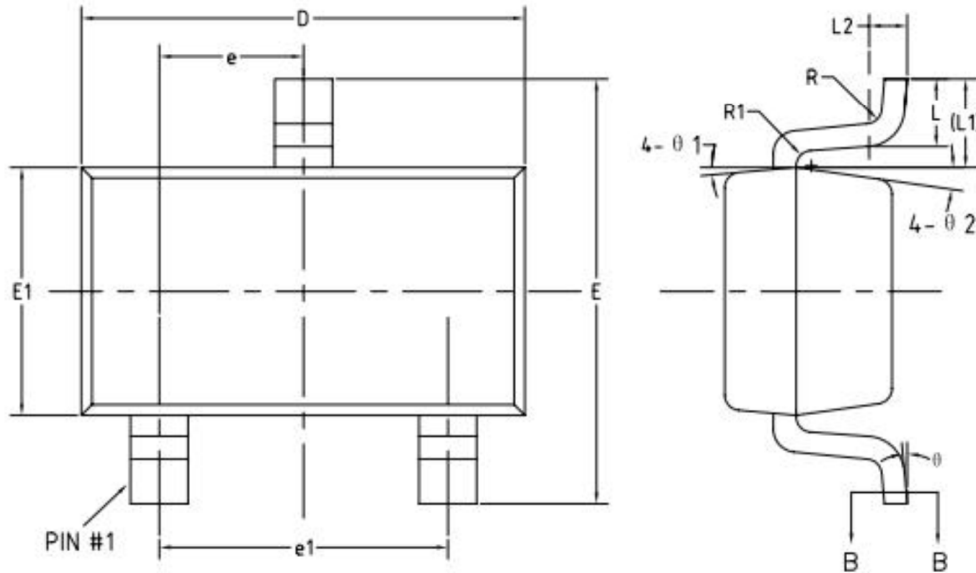


**T<sub>C</sub> - Case Temperature**  
Power Derating



**Normalized Thermal Transient Impedance, Junction-to-Foot**

SOT-23-3L PACKAGE OUTLINE



COMMON DIMENSIONS  
(UNITS OF MEASURE=MILLIMETER)

SYMBOL	MIN	TYP	MAX
A	-	-	1.50
A1	0.00	-	0.18
A2	0.85	1.10	1.35
A3	0.58	0.65	0.72
b	0.23	-	0.53
b1	0.20	0.40	0.50
c	0.09	-	0.22
c1	0.08	0.13	0.21
D	2.78	2.95	3.10
E	2.58	2.80	3.03
E1	1.55	1.65	1.78
e	0.83	0.95	1.07
e1	1.78	1.90	2.02
L	0.28	0.45	0.62
L1	0.59REF		
L2	0.25BSC		
R	0.04	-	-
R1	0.04	-	0.21
θ	0°	-	8°
θ 1	8°	10°	12°
θ 2	8°	10°	12°

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